



End of Life Notification

Laird Tpcm™ 580SP Phase Change Thermal Interface Material

September 1, 2022

Dear Laird Valued Customer:

This letter is to inform you that Laird™ Tpcm™ 580SP Screen Printable Phase Change Thermal Interface Material will be transitioning through an end of life (EOL) process. The primary reasons for implementing EOL is diminishing demand. We wish to alert you that the final buy date to submit a purchase order for this product will be March 31, 2023. Laird's final ship date will be October 31, 2023, approximately 14 months from now.

The replacement material is Laird™ Tpcm 200SP or Tpcm 780SP. See below for relevant specifications.

	Tpcm™ 580SP	Tpcm™ 200SP	Tpcm™ 780SP
Construction	Filled Non-Silicone Paste	Filled Non-Silicone Paste	Filled Non-Silicone Paste
Color	Grey	White	Grey
Density*	2.34 g/cc	3.2 g/cc	2.5 g/cc
Bulk Thermal Conductivity*	4.0 W/m-K	1.5 W/m-K	5.4 W/m-K
Thermal Resistance*			
10 psi & 70°C	°C-cm²/W	0.452°C-cm²/W	0.120°C-cm²/W
50 psi & 70°C	°C-cm²/W	0.316°C-cm²/W	0.085°C-cm²/W
Viscosity	52 Pa-s @25°C	20 Pa-s @25°C	35 Pa-s @25°C 50,000-100,000cPs @25°C
Operating Temperature Range*	-40°C to 125°C	-40°C to 125°C	-40°C to 125°C
Softening Temperature Range*	≈45°C to 70°C	≈45°C to 70°C	≈45°C to 70°C
Minimum Bondline Thickness*	N/A	N/A	25µm
Dielectric Constant*	N/A	N/A	22.3@1KHz, 22.9@1MHz
Volume Resistivity*	N/A	N/A	1.5x10 ¹³ Ω-cm

We thank you for your continued business and support. If you have any questions, please contact the Laird Performance Materials sales representative in your region.

Jim Latham

Product Manager - Thermal
Laird Performance Materials
DuPont Electronics & Industrial